Title (en)

SUPPORT AND/OR CLIP FOR SEMICONDUCTOR ELEMENTS, SEMICONDUCTOR COMPONENT, AND PRODUCTION METHOD

Title (de)

TRÄGER UND/ODER CLIP FÜR HALBLEITERELEMENTE, HALBLEITERBAUELEMENT UND VERFAHREN ZUR HERSTELLUNG

Title (fr)

SUPPORT ET/OU ÉTRIER POUR ÉLÉMENTS SEMI-CONDUCTEURS, ÉLÉMENT SEMI-CONDUCTEUR ET PROCÉDÉ DE FABRICATION

Publication

EP 3123502 A1 20170201 (DE)

Application

EP 15713178 A 20150326

Priority

- DE 102014104267 A 20140326
- DE 102014104819 A 20140404
- EP 2015056599 W 20150326

Abstract (en)

[origin: WO2015144835A1] The invention relates to a support and/or clip for at least one semiconductor element with at least one functional surface (10) for connecting to the semiconductor element. The invention is further characterized by at least one solder resist cavity (12) with at least one flank wall (13), in particular a straight flank wall (13), and a delimiting edge (14) which adjoins the flank wall (13) and delimits the functional surface (10) at least on one side. The delimiting edge (14) forms a protrusion (15) which protrudes past the functional surface (10) in order to retain solder, and/or the flank wall (13) forms an undercut (16) for retaining solder at the delimiting edge (14).

IPC 8 full level

H01L 21/67 (2006.01); **H01L 23/00** (2006.01); **H05K 3/34** (2006.01)

CPC (source: CN EP KR US)

H01L 21/4828 (2013.01 - US); **H01L 21/4842** (2013.01 - EP US); **H01L 21/67144** (2013.01 - CN EP KR US); **H01L 21/683** (2013.01 - CN); **H01L 21/68714** (2013.01 - CN); **H01L 23/49503** (2013.01 - US); **H01L 23/49524** (2013.01 - EP US); **H01L 23/49548** (2013.01 - EP US); **H01L 24/13** (2013.01 - KR US); **H01L 24/32** (2013.01 - KR US); **H01L 24/83** (2013.01 - US); **H05K 3/3452** (2013.01 - EP KR US); H01L 24/16 (2013.01 - EP); H01L 24/32 (2013.01 - EP); H01L 2224/10175 (2013.01 - EP); H01L 2224/131 (2013.01 - EP); H01L 2224/16245 (2013.01 - EP); H01L 2224/26175 (2013.01 - EP); H01L 2224/291 (2013.01 - EP); H01L 2224/32245 (2013.01 - EP US); H01L 2224/83801 (2013.01 - US); H01L 2924/13091 (2013.01 - EP KR US); H01L 2924/17151 (2013.01 - US); H05K 2201/09036 (2013.01 - EP KR US); H05K 2203/107 (2013.01 - US)

Citation (search report)

See references of WO 2015144835A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

DE 102014104819 A1 20151001; CN 106104784 A 20161109; EP 3123502 A1 20170201; JP 2017510991 A 20170413; KR 20160136405 A 20161129; US 2017110390 A1 20170420; WO 2015144835 A1 20151001

DOCDB simple family (application)

DE 102014104819 A 20140404; CN 201580014522 A 20150326; EP 15713178 A 20150326; EP 2015056599 W 20150326; JP 2016558343 A 20150326; KR 20167029450 A 20150326; US 201515129202 A 20150326